



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

TI-35623

Young-Joon Park, et al.

Examiner: TBD

Serial No.: 10/628,198

Art Unit: 2811

Filed: 07/28/03

For: Two Step Semiconductor Manufacturing Process for Copper Interconnects

**LETTER TO THE OFFICIAL DRAFTSPERSON**

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

*Karen Keagy* 11-3-03  
Karen Keagy Date

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Enclosed are **TWO (2)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Respectfully submitted,

*Rose Alyssa Keagy*  
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